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(54) PRINTED CIRCUIT MODULE AND ELECTRONIC DEVICE INCLUDING THE

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(57)ABSTRACT

An electronic device according to various embodiments may include: a display, a first circuit board disposed under the display, a first component and a second component disposed on one surface of the first circuit board, the first and second components each having different heights, a first interposer surrounding at least one side surface of the first component and disposed in a first region of the first circuit board, the first interposer part having a first height, a second interposer part surrounding at least one side surface of the second component and disposed in a second region of the first circuit board, the second interposer part having a second height different from the first height, a first second circuit board, at least a portion of which is spaced apart from the first region of the first circuit board, the first second circuit board including a first first portion bonded to the first interposer part, and a second second circuit board, at least a portion of which is spaced apart from the second region of the first circuit board, the second second circuit board including a first second portion bonded to the second interposer and spaced apart from the first second circuit board by a specified gap.

